

LN170WP38

Round Type

φ4.4 mm

■ Absolute Maximum Ratings $T_a = 25^\circ\text{C}$

- Yellow Green

Parameter	Symbol	Rating	Unit
Power dissipation	P_D	90	mW
Forward current	I_F	30	mA
Pulse forward current *	I_{FP}	150	mA
Reverse voltage	V_R	4	V
Operating ambient temperature	T_{opr}	-25 to +85	°C
Storage temperature	T_{stg}	-30 to +100	°C

Note) *: The condition of I_{FP} is duty 10%, Pulse width 1 msec.

■ Lighting Color

- Yellow Green
- Orange

- Orange

Parameter	Symbol	Rating	Unit
Power dissipation	P_D	90	mW
Forward current	I_F	30	mA
Pulse forward current *	I_{FP}	150	mA
Reverse voltage	V_R	3	V
Operating ambient temperature	T_{opr}	-25 to +85	°C
Storage temperature	T_{stg}	-30 to +100	°C

Note) *: The condition of I_{FP} is duty 10%, Pulse width 1 msec.

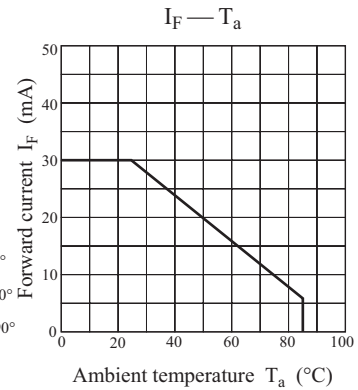
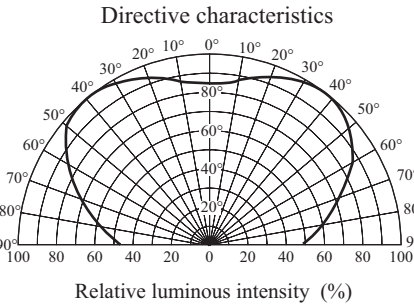
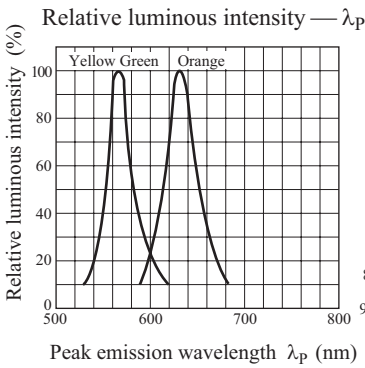
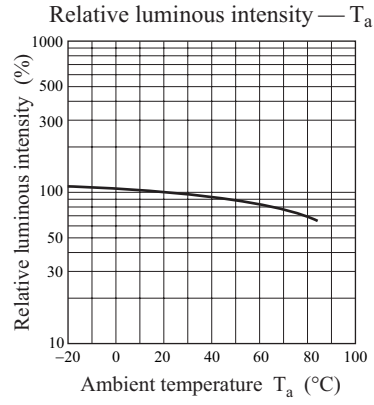
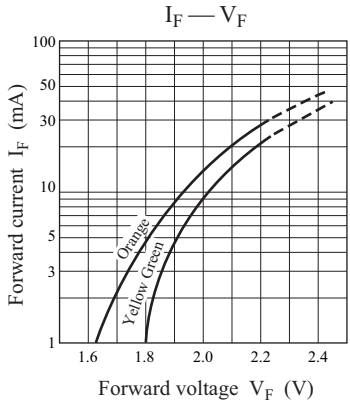
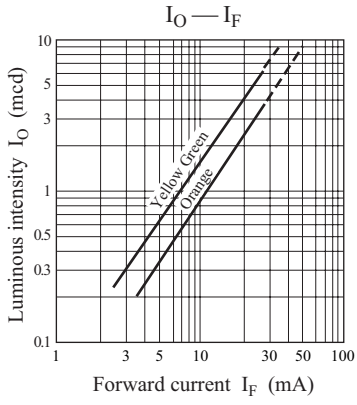
■ Electro-Optical Characteristics $T_a = 25^\circ\text{C}$

- Yellow Green

Parameter	Symbol	Conditions	Min	Typ	Max	Unit
Luminous intensity	I_O		0.8	4.0		mcd
Reverse current	I_R	$V_R = 4\text{ V}$			10	μA
Forward voltage	V_F	$I_F = 20\text{ mA}$		2.2	2.50	V
Peak emission wavelength	λ_p	$I_F = 20\text{ mA}$		565		nm
Spectral half band width	$\Delta\lambda$	$I_F = 20\text{ mA}$		30		nm

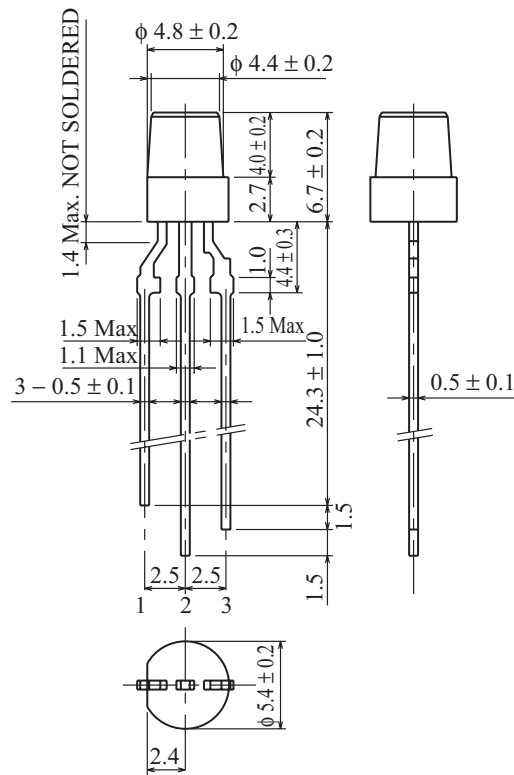
- Orange

Parameter	Symbol	Conditions	Min	Typ	Max	Unit
Luminous intensity	I_O		0.5	2.5		mcd
Reverse current	I_R	$V_R = 3\text{ V}$			10	μA
Forward voltage	V_F	$I_F = 20\text{ mA}$		2.1	2.45	V
Peak emission wavelength	λ_p	$I_F = 20\text{ mA}$		630		nm
Spectral half band width	$\Delta\lambda$	$I_F = 20\text{ mA}$		40		nm



■ Package (Unit: mm)

LLXFTN3SH702



• Pin name

- 1: Anode (Orange)
- 2: Cathode (Common)
- 3: Anode (Yellow Green)

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